# MSKSEMI 美森科













ESD

TSS

MOV

GDT

PIFD

SMF05C

**Product specification** 





#### **Features**

- IEC 61000-4-2 Level 4 ESD Protection
  -±12kV Contact Discharge
  - -±17kV Air Discharge
- 100W Peak pulse Power (8/20us)
- Low clamping voltage
- Working voltage: 5V
- Low leakage current
- RoHS compliant
- Protecting 5 unidirectional lines
- Capacitance: 100pF Typ.

## **Applications**

- Cellular Handsets and Accessories
- Cordless Phones
- Personal Digital Assistants (PDA's)
- Notebooks & Handhelds
- Digital Cameras
- Portable Instrumentation

#### **Reference News**

SOT-363	PIN Configuration	Marking
1 2 3		. 5C

### **Pin Configuration and Functions**

Pin	Name	Description	
1	IO1	Connect to I/O	
2	GND	Connect to GND	
3	IO2	Connect to I/O	
4	IO3	Connect to I/O	
5	IO4	Connect to I/O	
6	IO5	Connect to I/O	



## Absolute Maximum rating Over operating free-air temperature range (unless otherwise noted)

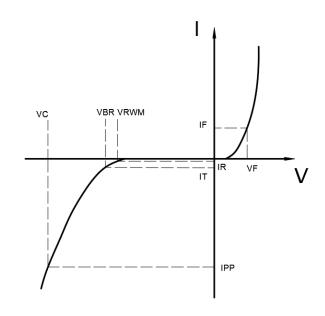
Parameters	Symbol	Min.	Max.	Unit
Peak pulse power (tp=8/20us)@25°C	$P_{pk}$	-	100	W
Peak pulse current (tp=8/20us)@25°C	I <sub>PP</sub>		8	А
ESD (IEC61000-4-2 air discharge) @25°C	V <sub>ESD</sub>	-	±17	kV
ESD (IEC61000-4-2 contact discharge) @25°C	$V_{\scriptscriptstyle{ESD}}$	-	±12	kV
Junction temperature	TJ	-	150	°C
Operating temperature	Тор	-40	125	°C
Storage temperature	T <sub>STG</sub>	-55	150	℃
Lead temperature	T∟	-	260	°C

# Electrical Characteristics At TA = 25°C unless otherwise noted

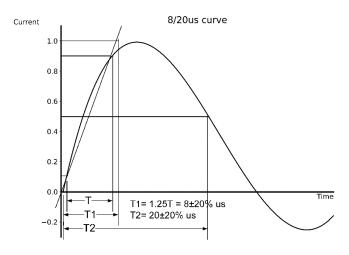
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Reverse Stand-off Voltage	V <sub>RWM</sub>				5	V
Reverse Breakdown Voltage	V <sub>BR</sub>	IT=1mA	6			V
Reverse Leakage Current	I <sub>R</sub>	V <sub>RWM</sub> =5V			1	uA
Clamping Voltage	Vc	I <sub>PP</sub> =1A; tp=8/20us		9.5		V
Clamping Voltage	Vc	I <sub>PP</sub> =8A; tp=8/20us		15		V
Junction Capacitance	C <sub>J</sub>	I/O to GND; VR=0V; f=1MHz		100		рF



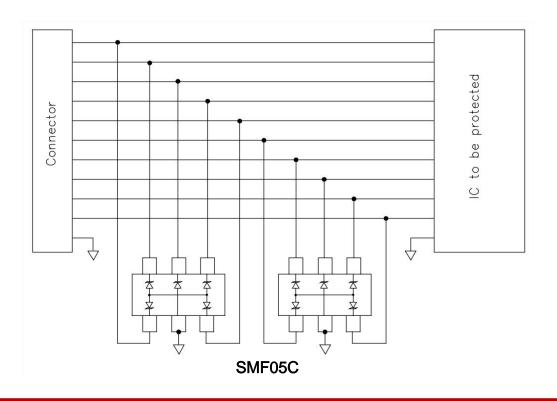
Symbol	Parameters
V <sub>RWM</sub>	Peak Reverse Working Voltage
I <sub>R</sub>	Reverse Leakage Current @ V <sub>RWM</sub>
$V_{BR}$	Breakdown Voltage @ I <sub>⊤</sub>
h	Test Current
<b>I</b> PP	Maximum Reverse Peak Pulse Current
Vc	Clamping Voltage @ IPP
l <sub>F</sub>	Forward Current
V <sub>F</sub>	Forward Voltage @ I₅



# **Typical Characteristic**

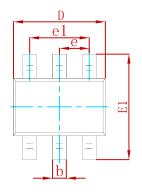


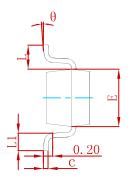
# **Typical Application**

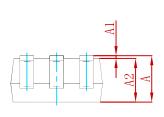




#### **PACKAGEMECHANICALDATA**

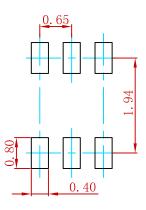






Symbol	Dimensions In Millimeters		Dimension	s In Inches
Symbol	Min	Max	Min	Max
Α	0.900	1.100	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.000	0.035	0.039
b	0.150	0.350	0.006	0.014
С	0.100	0.150	0.004	0.006
D	2.000	2.200	0.079	0.087
E	1.150	1.350	0.045	0.053
E1	2.150	2.400	0.085	0.094
е	0.650 TYP		0.026	S TYP
e1	1.200	1.400	0.047	0.055
L	0.525 REF		0.021	I REF
L1	0.260	0.460	0.010	0.018
θ	0°	8°	0°	8°

## **Suggested Pad Layout**



#### Note:

- 1.Controlling dimension:in millimeters. 2.General tolerance:± 0.05mm.
- 3. The pad layout is for reference purposes only.

## **Order information**

Orderable Device	Package	Packing Option
SMF05C	SOT-363	3000PCS



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